

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,056,766 B2
APPLICATION NO. : 10/731831
DATED : December 9, 2003
INVENTOR(S) : Hei Ming Shiu

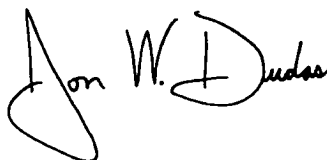
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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In Column 7, Line 11, Claim No. 14:
Change "dice, comprising" to --die, comprising--
In Column 7, Line 18, Claim No. 14:
Change "dice to the mold" to --die to the mold--
In Column 7, Line 19, Claim No. 14:
Change "of the dice have" to --of the die have--
In Column 7, Line 22, Claim No. 14:
Change "of the dice to" to --of the die to--
In Column 7, Line 24, Claim No. 14:
Change "dice;" to --die;--
In Column 7, Line 25, Claim No. 14:
Change "encapsulating the dice," to --encapsulating the die,--
In Column 7, Line 28, Claim No. 14:
Change "such that a bottom" to --such that bottom--
In Column 7, Line 30, Claim No. 14:
Change "encapsulated dice to" to --encapsulated die to--
In Column 8, Line 14, Claim No. 20:
Change "wherein the dice" to --wherein the die--
In Column 8, Line 15, Claim No. 20:
Change "side of the dice" to --side of the die--

Signed and Sealed this

Twentieth Day of May, 2008



JON W. DUDAS
Director of the United States Patent and Trademark Office